

## Abstract

A new type of suspension circuit electrical bonding pad is described for electrically and mechanically connecting process for the magnetic recording head. The new type of bonding pad will serve as the joint material as well as the joint interface. Thus there is no need to apply the conductive material in between the bonding pads and magnetic recording head terminals, consequently reducing the process leading time and simplifying the magnetic recording head assemble process.

Sub  
ac

**CONCLUSIONS**